



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



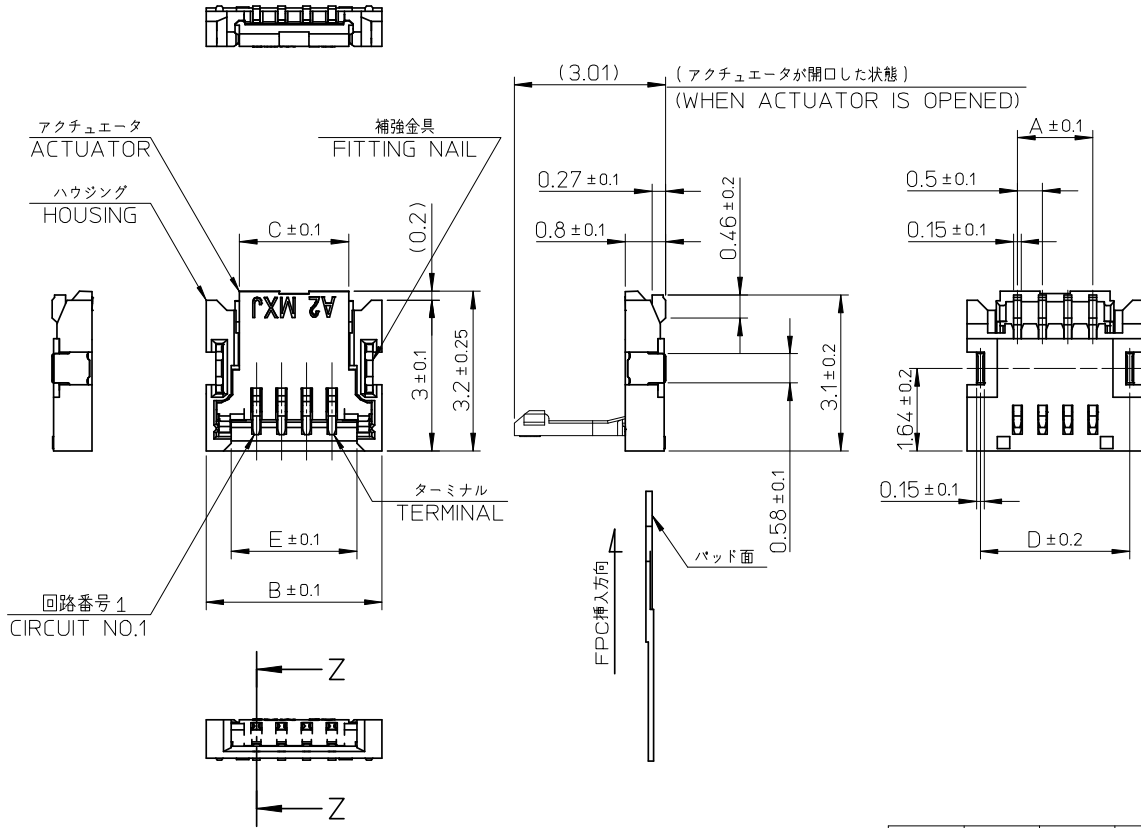
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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





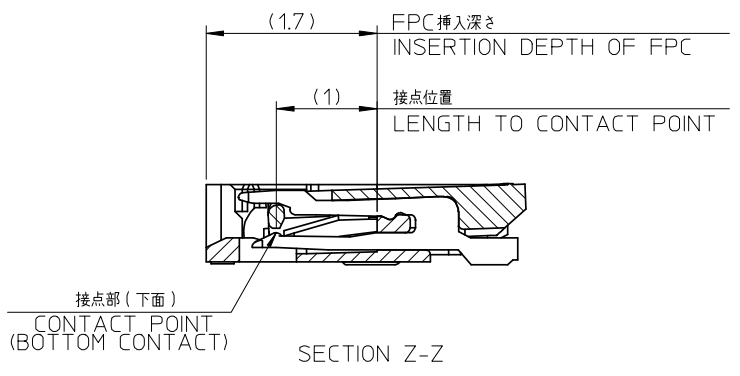
注記
NOTES:

1.材質
MATERIAL
ハウジング:耐熱性樹脂、ガラス充填、UL94V-0
HOUSING:HEAT RESISTANCE POLYMER,GLASS FILLED,UL94V-0
アクチュエータ:耐熱性樹脂、ガラス充填、UL94V-0
ACTUATOR:HEAT RESISTANCE POLYMER,GLASS FILLED,UL94V-0
ターミナル:銅合金(t=0.15)
TERMINAL:COPPER ALLOY (t=0.15)
補強金具:銅合金(t=0.15)
NAIL:COPPER ALLOY (t=0.15)

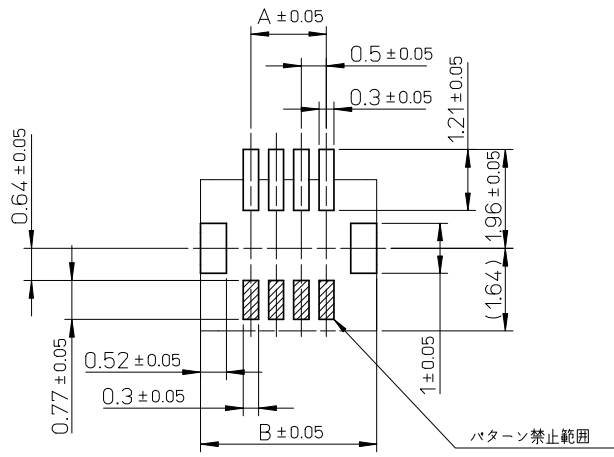
2.めっき仕様
PLATING
ターミナル: 部分金メッキ
接点部 0.1マイクロメートル以上
半田付け部 0.05マイクロメートル以上
TERMINAL : SEPARATED GOLD PLATING
CONTACT AREA 0.1 MICROMETER MINIMUM.
SOLDER TAIL AREA 0.05 MICROMETER MINIMUM.
下地 ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING ; NICKEL PLATING 1.0 MICROMETER MINIMUM.
補強金具: 錫メッキ 1.0マイクロメートル以上
NAIL : TIN PLATING 1.0 MICROMETER MINIMUM.
下地 ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING ; NICKEL PLATING 1.0 MICROMETER MINIMUM.

3.平坦度は、0.1mm以下とする。
TAILS AND NAILS COPLANARITY TO BE 0.1mm MAXIMUM.

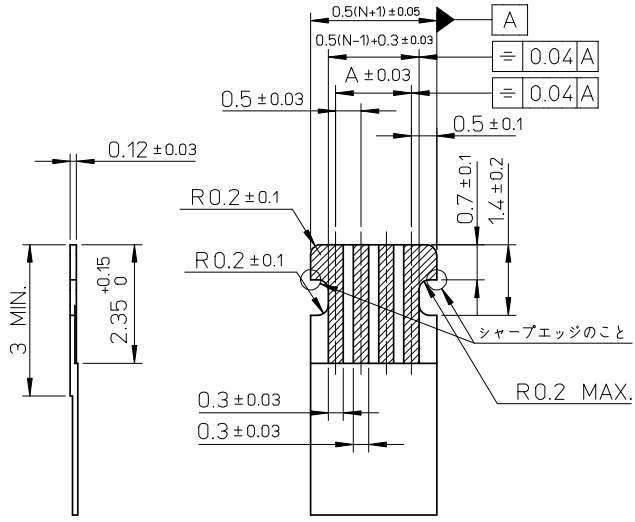
4.0	4.47	3.68	5.0	3.0	NOT AVAILABLE	NOT AVAILABLE	7
3.5	3.97	3.18	4.5	2.5	501461-0601	501461-0609	6
3.0	3.47	2.68	4.0	2.0	501461-0501	501461-0509	5
2.5	2.97	2.18	3.5	1.5	501461-0401	501461-0409	4
E	D	C	B	A	エンボス梱包品 EMBOSSED PACKAGING		製品番号 MATERIAL NO.
					ORDER No. オーダー番号		極数(N) CIRCUITS(N)



REVISED EC NO: J2008-4048 DRWN: MABEI 2008/06/13 CHKD: THARUYAMA 2008/06/16 APPR: NUKITA 2008/06/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY RSUMIYA	DATE 2004/11/10	TITLE 0.5 FPC CONN BACK FLIP HGT=0.8 HSG ASSY -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY HIRATA	DATE 2004/11/10	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 2004/11/10	DOCUMENT NO. SD-501461-001		
	ANGULAR ±1°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 2		
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



推奨基板寸法
RECOMMENDED P.C.BOARD PATTERN LAYOUT



推奨FPC寸法
RECOMMENDED FPC PATTERN LAYOUT

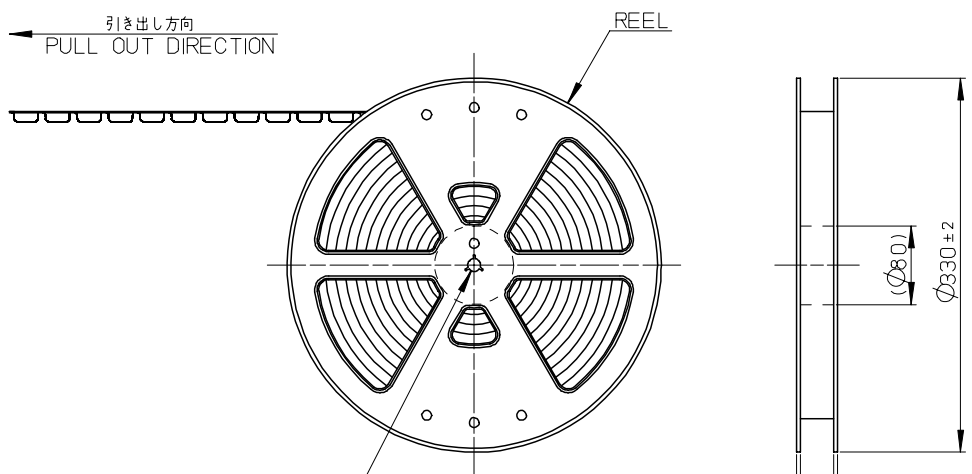
FPCについて：
 抜き方向は、導体側から補強板側を推奨します。
 補強フィルム材質は、ポリイミドを推奨します。
 接着剤は、熱硬化接着剤を推奨します。
 尚、接着剤の接点部への付着は、導通不良の原因となりますので染み出しが無いよう、お願いします。

ABOUT FPC:
 RECOMMENDED PUNCHER DIRECTION:
 FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.
 RECOMMENDED MATERIAL:
 STIFFNER FILM: POLYIMIDE
 BONDING AGENT: THERMOSETTING AGENT
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE MAY CAUSE
 THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED EC NO: J2008-4048 DRWN: MWABEI 2008/06/13 CHKD: THARUYAMA 2008/06/16 APPR: NUKITA 2008/06/16	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY RSUMIYA	DATE 2004/11/10	TITLE 0.5 FPC CONN BACK FLIP HGT=0.8 HSG ASSY -LEAD FREE-			
		10 OVER 30 UNDER	± 0.25	CHECKED BY HHIRATA	DATE 2004/11/10	MOLEX INCORPORATED			
		30 OVER	± 0.3	APPROVED BY MSASAO	DATE 2004/11/10				
		ANGULAR	± 1 °	MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-501461-001	SHEET NO. 2 OF 2			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

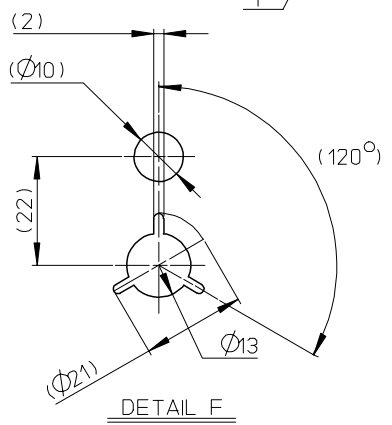
10 9 8 7 6 5 4 3 2 1

引き出し方向
PULL OUT DIRECTION



REEL

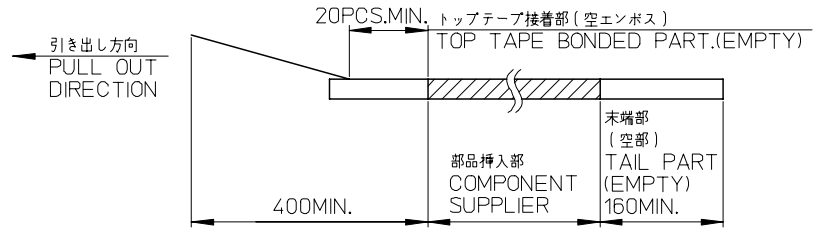
C ±1
D ±1



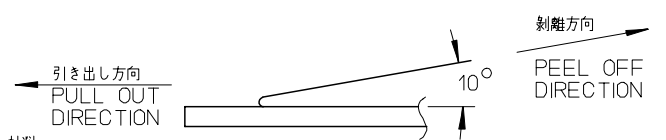
DETAIL F

NOTES

- 製品詳細寸法については製品単体図面を参照下さい。
RE DETAILED DIMENSION, SEE PRODUCT DRAWING.
- 梱包数量: 3000個/リール
NUMBER OF CONNECTORS 3000PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- トップテープの剥離強度: 0.1N~1.3N { 10gf~130gf }
(剥離強度は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N~1.3N(10gf~130gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.



- 材料
MATERIAL
キャリアテープ(CARRIRE TAPE): ホリスチレン (POLYSTYRENE)
トップテープ(TOP TAPE): PET, PE, PEF
リール(REEL): ホリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAILED>

501461-**01 MODEL NO.

REVISED EC NO: J2008-0606 DRWN: A0YAGI 2007/09/06 CHKD: THARUYAMA 2007/09/10 APPR: NUKITA 2007/09/10	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY RSUMIYA	DATE 2005/02/07	TITLE 0.5 FPC CONN BACK FLIP H=0.8 EMBSTP PKG -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY HIRATA	DATE 2005/02/07	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 2005/02/07	DOCUMENT NO. SD-501461-002	SHEET NO. 1 OF 2
	ANGULAR	±1	MATERIAL NO. SEE SHEET 2			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

E

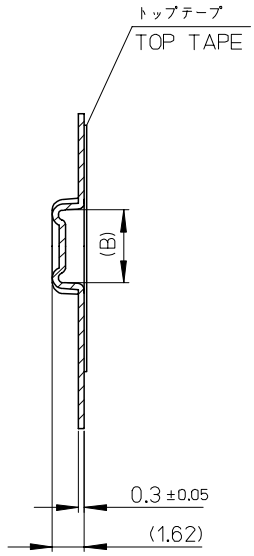
D

C

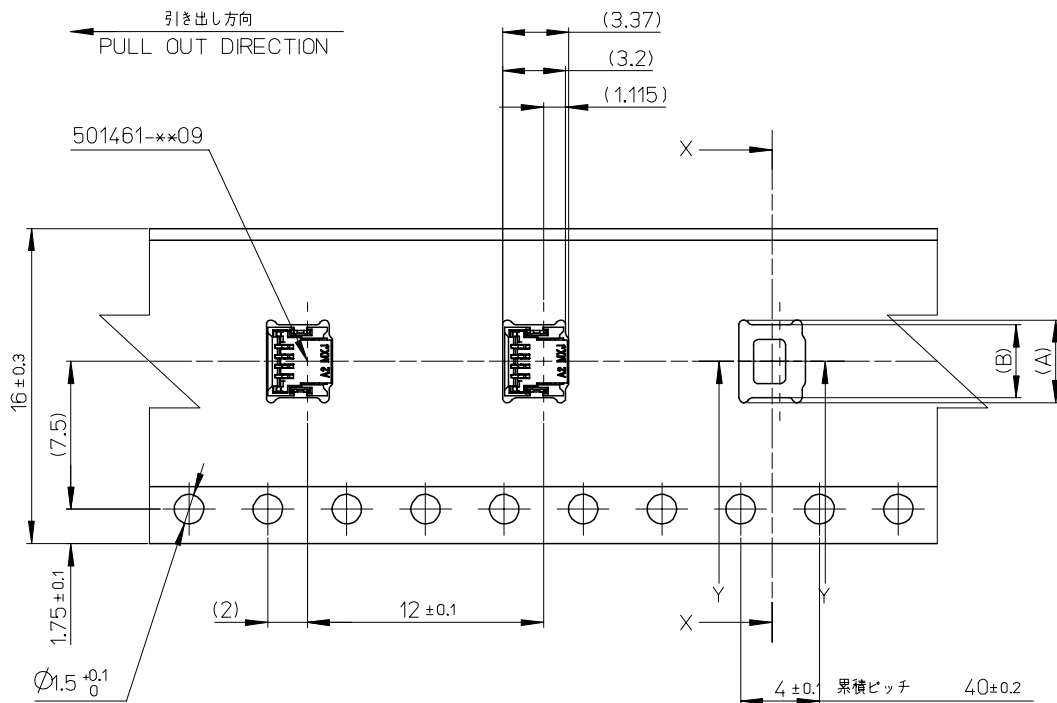
B

A

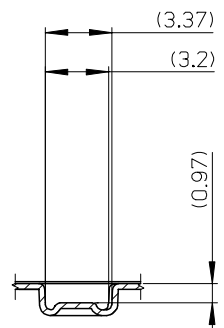
引き出し方向
PULL OUT DIRECTION



SECT. X-X



16mm幅キャリアテープ
16mm WIDTH CARRIER TAPE

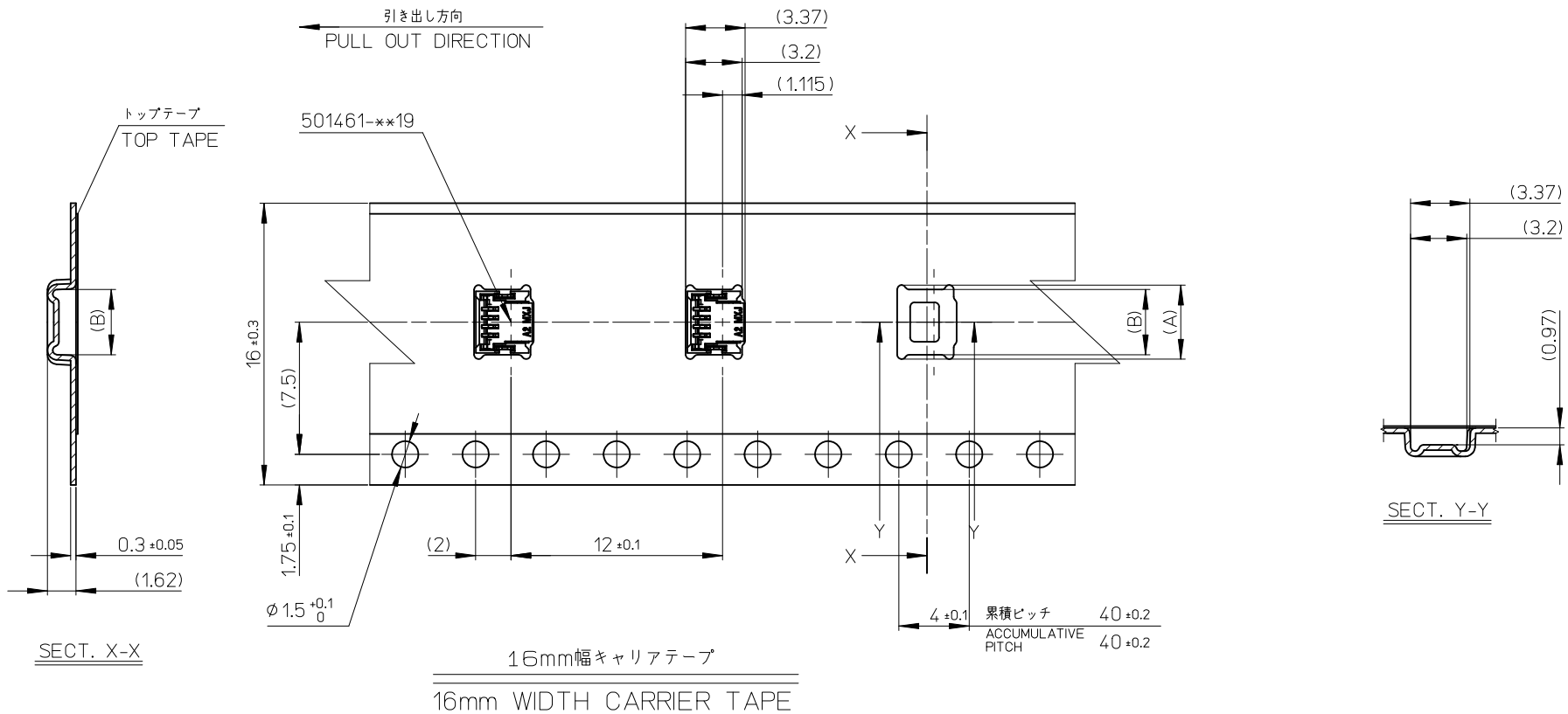


SECT. Y-Y

16	21.4	17.4	5.2	5.7	NOT AVAILABLE	7	
			4.7	5.2	501461-0601	6	
			4.2	4.7	501461-0501	5	
			3.7	4.2	501461-0401	4	
キャリアテープ幅 CARRIER TAPE WIDTH		D	C	(B)	(A)	MATERIAL NO.	極数 CIRCUITS

REVISED EC NO: J2008-0606 DRWN: A0YAGI 2007/09/06 CHKD: THARUYAMA 2007/09/10 APPR: NUKITA 2007/09/10	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER ± 0.2	DRAWN BY RSUMIYA	DATE 2005/02/07	TITLE 0.5 FPC CONN BACK FLIP H=0.8 EMBSTP PKG -LEAD FREE-	
	10 OVER 30 UNDER ± 0.25	CHECKED BY HIRATA	DATE 2005/02/07	MOLEX INCORPORATED	
	30 OVER ± 0.3	APPROVED BY MSASAO	DATE 2005/02/07	DOCUMENT NO. SD-501461-002	SHEET NO. 2 OF 2
	ANGULAR ± 1	MATERIAL NO. SEE TABLE			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1



16	21.4	17.4	4.7	5.2	501461-0611	6
16	21.4	17.4	4.2	4.7	501461-0511	5
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	(B)	(A)	MATERIAL NO.	極数 CIRCUITS

SEE SHEET 1 OF 2 EC NO: J2011-0042 DRWN: YKOBAYASHI 02 2010/07/09 CHKD: MATSUURA 2010/07/09 APPR: KMORIKAWA 2010/07/09	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	MODEL NO. 501461-**11
	10 UNDER	±0.2	DRAWN BY E. SATO	DATE 2009/03/24	TITLE 0.5 FPC CONN BACK FLIP H=0.8 EMBSTP PKG		
	10 OVER 30 UNDER	±0.25	CHECKED BY H. MATSUMOTO	DATE 2009/03/24	THIRD ANGLE PROJECTION		
	30 OVER	±0.3	APPROVED BY N. UKITA	DATE 2009/03/24	MOLEX INCORPORATED		
ANGULAR	±1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-501461-006	SHEET NO. 2 OF 2	
A	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					